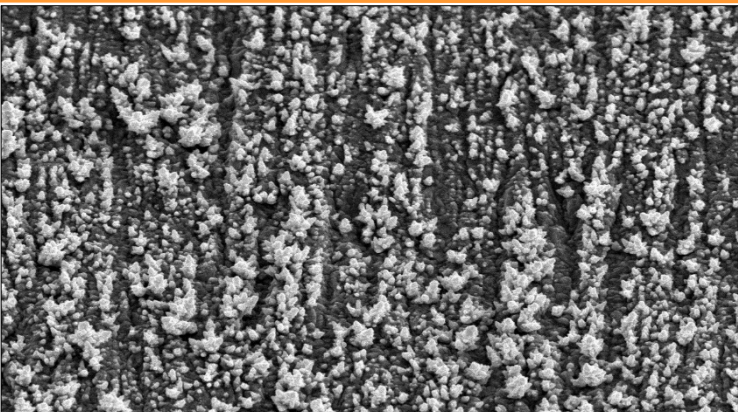


● Features

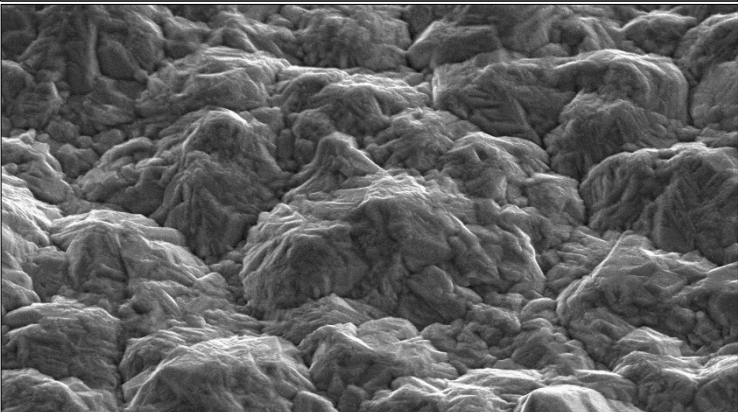
- *Very lower profile to improve SI performance.*
- *Special treatment to enhance peel strength.*
Micro copper-crystal treated for fine pitch process.
- *Excellent anti-oxidation and shelf life.*

● Applications

- *High speed server (PCIe G4).*
- *Networking , Telecom & Base station.*
- *Materials: Mid-loss up/ Very low loss up*
- *Oxide system preference: 1st: Low-etching/ 2nd: Non-etching*



35µm Foil Bonding-side SEM × 3,000



35µm Foil Resist-side SEM × 3,000

MEASURED PARAMETERS			UNITS	PRODUCT GAUGE					IPC	
Nominal Thickness			μm oz.	12 1/3	15 3/7	18 1/2	35 1	70 2	Specification IPC-4562A	Test Method IPC-TM-650
Area Weight			g/m ²	105±3	125±5	153±5	285±8	580±15	3.4.4	2.2.12
Bonding Side Contact Roughness	Rz	JIS B 0601	μm	≤2.3	≤2.3	≤2.3	≤2.3	≤2.3	-	2.2.17
Resist Side Contact Roughness	Rz	JIS B 0601	μm	≤4.5	≤5.0	≤5.5	≤7.0	≤11.0	-	2.2.17
Tensile Strength		RT	MPa (Kgf/mm ²)	≥294 (≥30)			≥284 (≥29)	≥254 (≥26)	3.5.1	2.4.18
		180°C		≥167 (≥17)						
Elongation		RT	%	≥5	≥6	≥8	≥15	≥20	3.5.3	
		180°C		≥5	≥6	≥8	≥10	≥14		
Peel Strength Low Loss Resin (RT)			N/mm (lbf/in)	≥0.40 (≥2.3)	≥0.43 (≥2.5)	≥0.52 (≥3.0)	≥0.61 (≥3.5)	≥0.70 (≥4.0)	3.5.4	2.4.8
Peel Strength FR-4 Resin System (RT)			N/mm (lbf/in)	≥0.61 (≥3.5)	≥0.70 (≥4.0)	≥0.79 (≥4.5)	≥1.14 (≥6.5)	≥1.40 (≥8.0)		

*The data above show actual values and are not guaranteed